



Semiconductor Device Type: N2X_SSOP_28_0.209in_MatteTin

					Package Homogeneous Materials				
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Sub-Component	Basic Substance	CAS Number	% Total Weight	mg/part	ppm
Wafer	Silicon	7440-21-3	7.50	17.18	75000
Leadframe	Copper	7440-50-8	10.65	24.40	106546
Leadframe	Iron	7439-89-6	0.25	0.58	2530
Leadframe	Lead	7439-92-1	0.00	0.00	11
Leadframe	Phosphorus	7723-14-0	0.01	0.02	88
Leadframe	Zinc	7440-66-6	0.01	0.03	110
Leadframe	Silver	7440-22-4	0.07	0.16	715
Die Attach Epoxy	Silver	7440-22-4	0.63	1.44	6300
Die Attach Epoxy	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	0.06	0.13	563
Die Attach Epoxy	Dodecyl acrylate	2156-97-0	0.06	0.13	563
Die Attach Epoxy	1,6-Hexanediol diacrylate	13048-33-4	0.00	0.01	38
Die Attach Epoxy	1-Methyl-2-pyrrolidone	872-50-4	0.00	0.01	38
Mold Compound	Silica Fused	60676-86-0	69.59	159.35	695858
Mold Compound	Epoxy Resin	Trade Secret	3.97	9.08	39650
Mold Compound	Epoxy, Cresol Novolac	29690-82-2	1.59	3.63	15860
Mold Compound	Phenol Resin	Trade Secret	3.97	9.08	39650
Mold Compound	Carbon Black	1333-86-4	0.20	0.45	1983
Wire	Gold	7440-57-5	0.20	0.46	2000
Anode Ball	Tin	7440-31-5	1.25	2.86	12500
TOTALS:			100.00	229.00	1,000,000
229.00 mg Total Mass					

17.18	(mg) Total	Wafer	% of Total Weight	7.50
	Silicon	7440-21-3	100.00	
Total 100.00				
25.19	(mg) Total	Leadframe	% of Total Weight	11.00
	Copper	7440-50-8	96.86	
	Iron	7439-89-6	2.30	
	Lead	7439-92-1	0.01	
	Phosphorus	7723-14-0	0.08	
	Zinc	7440-66-6	0.10	
	Silver	7440-22-4	0.65	
Total 100.00				
1.72	(mg) Total	Die Attach Epoxy	% of Total Weight	0.75
	Silver	7440-22-4	84.00	
	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	7.50	
	Dodecyl acrylate	2156-97-0	7.50	
	1,6-Hexanediol diacrylate	13048-33-4	0.50	
	1-Methyl-2-pyrrolidone	872-50-4	0.50	
Total 100.00				
181.60	(mg) Total	Mold Compound	% of Total Weight	79.30
	Silica Fused	60676-86-0	87.75	
	Epoxy Resin	Trade Secret	5.00	
	Epoxy, Cresol Novolac	29690-82-2	2.00	
	Phenol Resin	Trade Secret	5.00	
	Carbon Black	1333-86-4	0.25	
Total 100.00				
0.46	(mg) Total	Wire	% of Total Weight	0.20
	Gold	7440-57-5	100.00	
Total 100.00				
2.86	(mg) Total	Anode Ball	% of Total Weight	1.25
	Tin	7440-31-5	100.00	
Total 100.00				
229.00		Total	100.00	100.00

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